Thermal Radiaton: Planck's Law



Basic Relations

Frequency vAngular Frequency $\omega = 2\pi v$ Wavelength λ Wavevector magnitude $k = 2\pi/\lambda$ Wavevector $\mathbf{k} = (k_x, k_y, k_z)$

$$c = v\lambda$$
 $\implies \omega = ck = c\sqrt{k_x^2 + k_y^2 + k_z^2}$

 $\omega(k)$: Dispersion relation (linear)

How much energy in the cavity?

$$U = 2\sum_{n_x=1}^{\infty} \sum_{n_y=1}^{\infty} \sum_{n_z=1}^{\infty} \hbar \omega f(\omega, T) =$$

$$2\int_{0}^{\infty} \frac{dk_x}{(2\pi/2L_x)} \int_{0}^{\infty} \frac{dk_y}{(2\pi/2L_y)} \int_{0}^{\infty} \frac{dk_z}{(2\pi/2L_z)} \hbar \omega f(\omega, T)$$

$$= 2\int_{-\infty}^{\infty} \frac{dk_x}{(2\pi/L_x)} \int_{-\infty}^{\infty} \frac{dk_y}{(2\pi/L_y)} \int_{-\infty}^{\infty} \frac{dk_z}{(2\pi/L_z)} \hbar \omega f(\omega, T)$$

Thermal Radiaton: Planck's Law

$$U = \frac{2V}{8\pi^3} \int_{-\infty-\infty-\infty}^{\infty} \int d\omega f(\omega, T) dk_x dk_y dk_z$$
$$= \frac{2V}{8\pi^3} \int_{0}^{\infty} \hbar \omega f(\omega, T) 4\pi k^2 dk$$
$$= \frac{2V}{8\pi^3} \int_{0}^{\infty} \hbar \omega f(\omega, T) 4\pi \left(\frac{\omega}{c}\right)^2 d\left(\frac{\omega}{c}\right)$$
$$\frac{U}{V} = \int_{0}^{\infty} \hbar \omega f(\omega, T) \frac{\omega^2}{\pi^2 c^3} d\omega$$
$$= \int_{0}^{\infty} \hbar \omega f(\omega, T) D(\omega) d\omega$$
$$= \int_{0}^{\infty} u(\omega) d\omega$$

 $D(\omega)$ -density of states per unit volume per unit angular frequency interval

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Energy density per ω interval

$$u(\omega) = \hbar \omega f(\omega, T) D(\omega)$$

 $=\frac{\hbar\omega^{3}}{\pi^{2}c^{3}}\frac{1}{\exp\left(\frac{\hbar\omega}{k_{B}T}\right)-1}$ Planck's law

Intensity: energy flux per unit solid angle

$$\int dA_{p} I(\omega) = \frac{C}{2}$$

$$\frac{du(\omega)}{4\pi} = \frac{\hbar\omega^3}{4\pi^3 c^2} \frac{1}{\exp\left(\frac{\hbar\omega}{k}\right)}$$

Solid Angle

whole space

Per unit wavelength interval

$$d\Omega = \frac{dA_p}{R^2}$$

4π

 $I(\lambda) = \left| \frac{I(\omega)d\omega}{d\lambda} \right| = \frac{4\pi c\hbar}{\lambda^5} \frac{1}{\exp\left(\frac{2\pi\hbar c}{k_B T\lambda}\right) - 1}$

Planck's law



Introduction to Thermoelectricity

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http://www.sil.si.edu/silpublications/dibner-library-lectures/scientific-discoveries/text-lecture.htm

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Jean Charles Athanase Peltier 1785-1845

Peltier Effect: Discovered in 1834 An electrical current creates a cooling or heating effect at the junction depending on the direction of current flow.

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Thomson Effect





Thomson effect predicted, 1855

William Thomson (Lord Kelvin) 1824 – 1907

http://www.sil.si.edu/silpublications/dibner-library-lectures/scientific-discoveries/text-lecture.htm

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Peltier Effect



Q (**Peltier**) = $(\Pi_1 - \Pi_2)$ **J**

Heating and cooling at junctions Reversible with current direction

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- Charge diffusion under a temperature gradient
- Built-in potential resisting diffusion

$$S = -\Delta V / \Delta T = -(V_{hot} - V_{cold}) / (T_{hot} - T_{cold})$$

S --- Seebeck Coefficient

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Properties are Temperature Dependent

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Thermoelectric Devices



COLD SIDE



HOT SIDE





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Performance of Thermoelectric Devices

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Device Analysis: Cooling



- Ideal Devices
 - No Joule Heating, No Heat Conduction

 $\mathbf{Q}_{\mathbf{c}} = (\boldsymbol{\Pi}_{\mathbf{p}} \textbf{-} \boldsymbol{\Pi}_{\mathbf{n}}) \textbf{\bullet} \mathbf{I}$

• Real Devices:

Joule Heating & Heat Conduction

$$\mathbf{Q}_{c} = (\Pi_{p} - \Pi_{n}) \cdot \mathbf{I} - \mathbf{I}^{2} \mathbf{R}/2 - \mathbf{K} (\mathbf{T}_{h} - \mathbf{T}_{c})$$

Electrical Resistance Thermal Conductance

$$R = \frac{L_p \rho_p}{A_p} + \frac{L_n \rho_n}{A_n}$$

$$K = \frac{k_p A_p}{L_p} + \frac{k_n A_n}{L_n}$$

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Optimize Current:

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Figure of Merit Z

$$KR = \left(\frac{L_p \rho_p}{A_p} + \frac{L_n \rho_n}{A_n}\right) \left(\frac{k_p A_p}{L_p} + \frac{k_n A_n}{L_n}\right)$$

 $(KR)_{min} = (\sqrt{k_p \rho_p} + \sqrt{k_n \rho_n})^2$ when $\frac{L_n A_p}{L_n A_n}$

$$\frac{L_n A_p}{L_p A_n} = \left(\frac{\rho_p k_n}{\rho_n k_p}\right)^{1/2}$$

 $Z_{\max} = \frac{\left(\frac{S_p - S_n}{k_p}\right)^2}{\left(\sqrt{k_p \rho_p} + \sqrt{k_n \rho_n}\right)^2}$ For a single material: $Z = \frac{S^2}{\rho k} = \frac{\sigma S^2}{k_p}$

In a device, pn pairs are used:

- (1) Areas of each type of legs need to be optimized
- (2) Two types of legs should have comparable properties
- (3) Current input to the device needs to be optimized

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Typical Number

• Bi_2Te_3 -based materials ~300 K

Device Leg: 1 mm x 1 mm x 2 mm





Temperature Dependence of Properties

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Thermoelectric Power Generation

Efficiency

$$\eta = \left(1 - \frac{T_c}{T_h}\right) \frac{\sqrt{1 + ZT_{ave}} - 1}{\sqrt{1 + ZT_{ave}}} + \frac{T_c}{T_h}$$
$$T + T_t$$

$$T_{ave} = \frac{1_c + 1_h}{2}$$

Constant Properties



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Thermoelectric Refrigeration Coefficient of Performance $COP = \frac{T_c}{T_h - T_c} \frac{\sqrt{1 + ZT_{ave}} - T_h / T_c}{\sqrt{1 + ZT_{ave}} + 1}$ **CARNOT CYCLE** STIRLING REFRIGERATORS HOUSEHOLD **REFRIGERATORS & AIR-CONDITIONERS** THERMOELECTRIC **REFRIGERATORS** O STIRLING 24⁷¹⁰ **Ç**RYOCOOLERS 0.5 1.2 .8 2.0 1.4 1.6 TEMPERATURE RATIO (T /T _____)

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Current and Potential Applications

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Commercial Thermoelectric Devices

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Power Generators from Hi-Z

Coolers from Marlow Industries

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Current Applications in Refrigeration

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Current Applications in Power Generation

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System Consideration



Sometimes, thermal systems more expansive Nancengineering Group –WARREN M. ROHSENOW HEAT AND MASS TRANSFER LABORATORY, MIT





Prototypes

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